



OPA244 OPA2244 OPA4244

MicroPower, Single-Supply **OPERATIONAL AMPLIFIERS** MicroAmplifier™ Series

FEATURES

MicroSIZE PACKAGES OPA244 (Single): SOT-23-5 OPA2244 (Dual): MSOP-8 OPA4244 (Quad): TSSOP-14

● *Micro*POWER: I_Q = 50μA/channel SINGLE SUPPLY OPERATION WIDE BANDWIDTH: 430kHz

WIDE SUPPLY RANGE: Single Supply: 2.2V to 36V Dual Supply: $\pm 1.1V$ to $\pm 18V$

APPLICATIONS

- BATTERY POWERED SYSTEMS
- PORTABLE EQUIPMENT
- PCMCIA CARDS
- BATTERY PACKS AND POWER SUPPLIES
- CONSUMER PRODUCTS

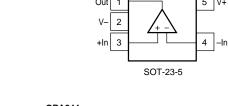
OPA244 Out 2 +In 3 SOT-23-5

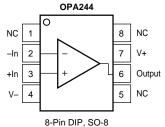
DESCRIPTION

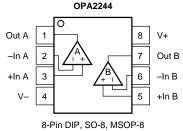
The OPA244 (single), OPA2244 (dual), and OPA4244 (quad) op amps are designed for very low quiescent current (50µA/channel), yet achieve excellent bandwidth. Ideal for battery powered and portable instrumentation, all versions are offered in micro packages for space-limited applications. The dual and quad versions feature completely independent circuitry for lowest crosstalk and freedom from interaction, even when overdriven or overloaded.

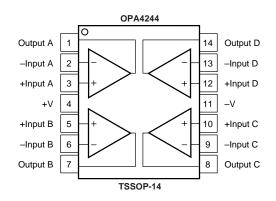
The OPA244 series is easy to use and free from phase inversion and overload problems found in some other op amps. These amplifiers are stable in unity gain and excellent performance is maintained as they swing to their specified limits. They can be operated from single (+2.2V to +36V) or dual supplies ($\pm 1.1V$ to $\pm 18V$). The input common-mode voltage range includes ground—ideal for many single supply applications. All versions have similar performance. However, there are some differences, such as common-mode rejection. All versions are interchangeable in most applications.

All versions are offered in miniature, surface-mount packages. OPA244 (single version) comes in the tiny 5-lead SOT-23-5 surface mount, SO-8 surface mount, and 8-pin DIP. OPA2244 (dual version) is available in the MSOP-8 surface mount, SO-8 surface-mount, and 8-pin DIP. The OPA4244 (quad) comes in the TSSOP-14 surface mount. They are fully specified from -40°C to +85°C and operate from -55°C to +125°C. A SPICE Macromodel is available for design analysis.









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SPECIFICATIONS: $V_S = +2.6V$ to +36V

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$

At T_A = +25°C, R_L = 20k Ω connected to ground, unless otherwise noted.

PARAMETER			OI	OPA244NA, PA, UA					
		CONDITION	MIN	TYP ⁽¹⁾	MAX	UNITS			
OFFSET VOLTAGE Input Offset Voltage $T_A = -40^{\circ}C \text{ to } 85^{\circ}C$ vs Temperature vs Power Supply $T_A = -40^{\circ}C \text{ to } 85^{\circ}C$	V _{OS} dV _{OS} /dT PSRR	$V_S = \pm 7.5V$, $V_{CM} = 0$ $T_A = -40^{\circ}C \text{ to } 85^{\circ}C$ $V_S = +2.6V \text{ to } +36V$ $V_S = +2.6V \text{ to } +36V$		±0.7 ± 4 5	±1.5 ±2 50 50	mV mV μV/°C μV/V μV/V			
INPUT BIAS CURRENT Input Bias Current Input Offset Current	I _B I _{OS}	$V_{CM} = V_S/2$ $V_{CM} = V_S/2$		-10 ±1	−25 ±10	nA nA			
NOISE Input Voltage Noise, f = 0.1kHz t Input Voltage Noise Density, f = Current Noise Density, f = 1kHz	I			0.4 22 40		μVp-p nV/√Hz fA/√Hz			
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection $T_A = -40^{\circ}\text{C}$ to 85°C	V _{CM} CMRR	$V_S = \pm 18V$, $V_{CM} = -18V$ to +17.1V $V_S = \pm 18V$, $V_{CM} = -18V$ to +17.1V	0 84 84	98	(V+) - 0.9	V dB dB			
INPUT IMPEDANCE Differential Common-Mode				10 ⁶ 2 10 ⁹ 2		Ω pF Ω pF			
OPEN-LOOP GAIN Open-Loop Voltage Gain T _A = -40°C to 85°C	A _{OL}	$V_O = 0.5V$ to $(V+) - 0.9$ $V_O = 0.5V$ to $(V+) - 0.9$	86 86	106		dB dB			
FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Settling Time 0.01% Overload Recovery Time	GBW SR	G = 1 10V Step $V_{IN} \cdot Gain = V_{S}$		430 -0.1/+0.16 150 8		kHz V/μs μs μs			
OUTPUT Voltage Output, Positive $T_A = -40^{\circ}C$ to $85^{\circ}C$ Voltage Output, Negative $T_A = -40^{\circ}C$ to $85^{\circ}C$ Voltage Output, Positive $T_A = -40^{\circ}C$ to $85^{\circ}C$ Voltage Output, Negative $T_A = -40^{\circ}C$ to $85^{\circ}C$ Short-Circuit Current Capacitive Load Drive	V _O I _{SC} C _{LOAD}	$\begin{array}{l} A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ V_S/2 \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ V_S/2 \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ V_S/2 \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ V_S/2 \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ \end{array}$	(V+) - 0.9 (V+) - 0.9 0.5 0.5	(V+) - 0.75 (V+) - 0.75 0.2 0.2 (V+) - 0.75 (V+) - 0.75 0.1 -25/+12 see Typical Cur	ve	V V V V V V mA			
POWER SUPPLY Specified Voltage Range Minimum Operating Voltage Quiescent Current $T_A = -40^{\circ}C \text{ to } 85^{\circ}C$	V _s	$T_A = -40$ °C to 85°C $I_O = 0$ $I_O = 0$	+2.6	+2.2 50	+36 60 70	V V μΑ μΑ			
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance SOT-23-5 Surface-Mount SO-8 Surface-Mount 8-Pin DIP	$ heta_{ extsf{JA}}$		-40 -55 -65	200 150 100	85 125 150	°C °C °C/W °C/W °C/W			

NOTE: (1) $V_S = +15V$.

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SPECIFICATIONS: $V_S = +2.6V$ to +36V

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$

At T_A = +25°C, R_L = 20k Ω connected to ground, unless otherwise noted.

			OP	OPA2244EA, PA, UA				
PARAMETER		CONDITION	MIN	TYP ⁽¹⁾	MAX	UNITS		
OFFSET VOLTAGE Input Offset Voltage $T_A = -40^{\circ}C \text{ to } 85^{\circ}C$ vs Temperature vs Power Supply $T_A = -40^{\circ}C \text{ to } 85^{\circ}C$ Channel Separation	V _{OS} dV _{OS} /dT PSRR	$V_S = \pm 7.5 \text{V}, V_{CM} = 0$ $T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C}$ $V_S = +2.6 \text{V to } +36 \text{V}$ $V_S = +2.6 \text{V to } +36 \text{V}$		±0.7 ± 4 5	±1.5 ±2 50 50	mV mV μV/°C μV/V μV/V dB		
INPUT BIAS CURRENT Input Bias Current Input Offset Current NOISE	I _B I _{OS}	$V_{CM} = V_S/2$ $V_{CM} = V_S/2$		-10 ±1	-25 ±10	nA nA		
Input Voltage Noise, f = 0.1kHz to Input Voltage Noise Density, f = 1kHz Current Noise Density, f = 1kHz				0.4 22 40		μVp-p nV/√Hz fA/√Hz		
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection $T_A = -40^{\circ}\text{C}$ to 85°C	V _{CM} CMRR	$V_S = \pm 18V$, $V_{CM} = -18V$ to +17.1V $V_S = \pm 18V$, $V_{CM} = -18V$ to +17.1V	0 72 72	98	(V+) - 0.9	V dB dB		
INPUT IMPEDANCE Differential Common-Mode				10 ⁶ 2 10 ⁹ 2		Ω pF Ω pF		
OPEN-LOOP GAIN Open-Loop Voltage Gain $T_A = -40$ °C to 85°C	A _{OL}	$V_O = 0.5V$ to $(V+) - 0.9$ $V_O = 0.5V$ to $(V+) - 0.9$	86 86	106		dB dB		
FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Settling Time 0.01% Overload Recovery Time	GBW SR	G = 1 10V Step $V_{IN} \cdot Gain = V_{S}$		430 -0.1/+0.16 150 8		kHz V/μs μs μs		
OUTPUT Voltage Output, Positive $T_A = -40^{\circ}C$ to $85^{\circ}C$ Voltage Output, Negative $T_A = -40^{\circ}C$ to $85^{\circ}C$ Voltage Output, Positive $T_A = -40^{\circ}C$ to $85^{\circ}C$ Voltage Output, Negative $T_A = -40^{\circ}C$ to $85^{\circ}C$ Voltage Output, Negative $T_A = -40^{\circ}C$ to $85^{\circ}C$ Short-Circuit Current Capacitive Load Drive	Vo I _{SC} C _{LOAD}	$\begin{array}{l} A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{V}_S/2 \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{V}_S/2 \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{V}_S/2 \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{V}_S/2 \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ \text{to} \ \text{Ground} \\ A_{OL} \geq 80 \text{dB}, \ R_L = 20 \text{k}\Omega \ d$	(V+) - 0.9 (V+) - 0.9 0.5 0.5	(V+) - 0.75 (V+) - 0.75 0.2 0.2 (V+) - 0.75 (V+) - 0.75 0.1 0.1 -25/+12 lee Typical Cur	ve	V V V V V V V mA		
POWER SUPPLY Specified Voltage Range Minimum Operating Voltage Quiescent Current (per amplifier) $T_A = -40^{\circ}C \text{ to } 85^{\circ}C$	V _S	$T_A = -40^{\circ}C \text{ to } 85^{\circ}C$ $I_O = 0$ $I_O = 0$	+2.6	+2.2 40	+36 50 63	V V μΑ μΑ		
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance MSOP-8 Surface-Mount SO-8 Surface-Mount 8-Pin DIP	$ heta_{\sf JA}$		-40 -55 -65	200 150 100	85 125 150	°C °C °C/W °C/W °C/W		

NOTE: (1) $V_S = +15V$.

SPECIFICATIONS: $V_S = +2.6V$ to +36V

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$

At T_A = +25°C, R_L = 20k Ω connected to ground, unless otherwise noted.

PARAMETER	CONDITION	MIN	TYP ⁽¹⁾	MAX	UNITS
OFFSET VOLTAGE Input Offset Voltage V_{OS} $T_A = -40^{\circ}C$ to $85^{\circ}C$ vs Temperature dV_{OS}/dT vs Power Supply PSRR $T_A = -40^{\circ}C$ to $85^{\circ}C$ Channel Separation	$V_S = \pm 7.5V$, $V_{CM} = 0$ $T_A = -40^{\circ}C \text{ to } 85^{\circ}C$ $V_S = +2.6V \text{ to } +36V$ $V_S = +2.6V \text{ to } +36V$		±0.7 ± 4 5	±1.5 ±2 50 50	mV mV μV/°C μV/V μV/V dB
INPUT BIAS CURRENT Input Bias Current I _B Input Offset Current I _{OS}	$V_{CM} = V_S/2$ $V_{CM} = V_S/2$		-10 ±1	-25 ±10	nA nA
$\begin{tabular}{ll} \textbf{NOISE} \\ \textbf{Input Voltage Noise, f = 0.1kHz to 10kHz} \\ \textbf{Input Voltage Noise Density, f = 1kHz} \\ \textbf{Current Noise Density, f = 1kHz} \\ \end{tabular} \begin{tabular}{ll} \textbf{e}_n \\ \textbf{i}_n \\ \end{tabular}$			0.4 22 40		μVp-p nV/√Hz fA/√Hz
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection $T_A = -40^{\circ}C$ to $85^{\circ}C$ CMRR	$V_S = \pm 18V$, $V_{CM} = -18V$ to +17.1V $V_S = \pm 18V$, $V_{CM} = -18V$ to +17.1V	0 82 82	104	(V+) - 0.9	V dB dB
INPUT IMPEDANCE Differential Common-Mode			10 ⁶ 2 10 ⁹ 2		Ω pF Ω pF
OPEN-LOOP GAIN Open-Loop Voltage Gain $T_A = -40^{\circ}C$ to $85^{\circ}C$	$V_O = 0.5V$ to $(V+) - 0.9$ $V_O = 0.5V$ to $(V+) - 0.9$	86 86	106		dB dB
FREQUENCY RESPONSE Gain-Bandwidth Product GBW Slew Rate SR Settling Time 0.01% Overload Recovery Time	G = 1 10V Step V _{IN} • Gain = V _S		430 -0.1/+0.16 150 8		kHz V/μs μs μs
OUTPUT Voltage Output, Positive $T_A = -40^{\circ}\text{C}$ to 85°C Voltage Output, Negative $T_A = -40^{\circ}\text{C}$ to 85°C Voltage Output, Negative $T_A = -40^{\circ}\text{C}$ to 85°C Short-Circuit Current I_{SC} Capacitive Load Drive	$\begin{array}{c} A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ V_S/2 \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ V_S/2 \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ V_S/2 \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ V_S/2 \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ A_{OL} \geq 80 dB, \ R_L = 20 k\Omega \ to \ Ground \\ \end{array}$	(V+) - 0.9 (V+) - 0.9 0.5 0.5	(V+) - 0.75 (V+) - 0.75 0.2 0.2 (V+) - 0.75 (V+) - 0.75 0.1 0.1 -25/+12 see Typical Cur	ve	V V V V V V mA
POWER SUPPLY Specified Voltage Range V_S Minimum Operating Voltage Quiescent Current (per amplifier) I_Q $T_A = -40$ °C to 85°C	$T_A = -40$ °C to 85°C $I_O = 0$ $I_O = 0$	+2.6	+2.2 40	+36 60 70	V V μΑ μΑ
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance θ_{JA} TSSOP-14 Surface Mount		-40 -55 -65	100	85 125 150	°C °C °C °C/W

NOTE: (1) $V_S = +15V$.

ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage, V+ to V	36V
Input Voltage Range ⁽²⁾	(V-) - 0.3V to (V+) + 0.3V
Input Current ⁽²⁾	10mA
Output Short-Circuit(3)	Continuous
Operating Temperature	55°C to +125°C
Storage Temperature	65°C to +150°C
Junction Temperature	150°C
Lead Temperature (soldering, 10s)	300°C
ESD Capability	2000V

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. (2) Inputs are diode-clamped to the supply rails and should be current-limited to 10mA or less if input voltages can exceed rails by more than 0.3V. (3) Short-circuit to ground, one amplifier per package.



This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

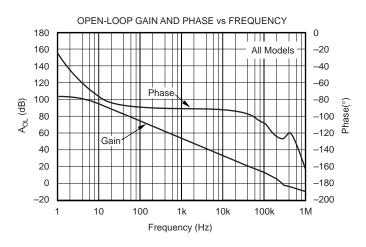
PACKAGE/ORDERING INFORMATION

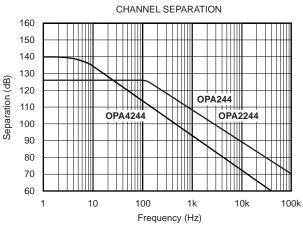
PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER ⁽¹⁾	TRANSPORT MEDIA
Single OPA244NA " OPA244PA OPA244UA	SOT-23-5 Surface-Mount " 8-Pin DIP SO-8 Surface-Mount "	331 " 006 182	-40°C to +85°C -40°C to +85°C -40°C to +85°C	A44 " OPA244PA OPA244UA "	OPA244NA/250 OPA244NA/3K OPA244PA OPA244UA OPA244UA/2K5	Tape and Reel Tape and Reel Rails Rails Tape and Reel
Dual OPA2244EA " OPA2244PA OPA2244UA	MSOP-8 Surface-Mount " 8-Pin DIP SO-8 Surface-Mount "	337 " 006 182	-40°C to +85°C -40°C to +85°C -40°C to +85°C	A44 " OPA2244PA OPA2244UA	OPA2244EA/250 OPA2244EA/2K5 OPA2244PA OPA2244UA OPA2244UA/2K5	Tape and Reel Tape and Reel Rails Rails Tape and Reel
Quad OPA4244EA	TSSOP-14 Surface-Mount	357 "	-40°C to +85°C	OPA4244EA	OPA4244EA/250 OPA4244EA/2K5	Tape and Reel Tape and Reel

NOTE: (1) Products followed by a slash (/) are only available in Tape and Reel in the quantities indicated (e.g., /250 indicates 250 devices per reel). Ordering 3000 pieces of "OPA244NA/3K" will get a single 3000 piece Tape and Reel.

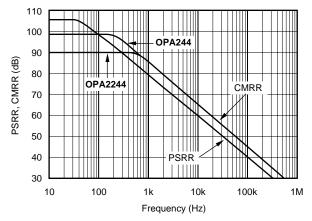
TYPICAL PERFORMANCE CURVES

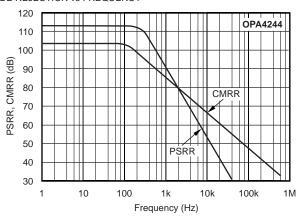
At T_A = 25°C, V_S = +15V, and R_L = 20k Ω connected to Ground, unless otherwise noted.

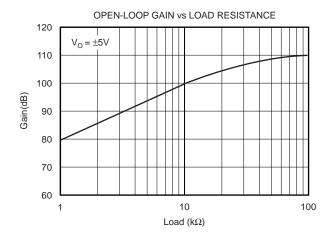


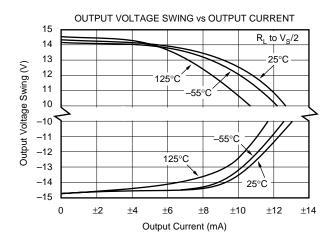


POWER SUPPLY AND COMMON-MODE REJECTION vs FREQUENCY

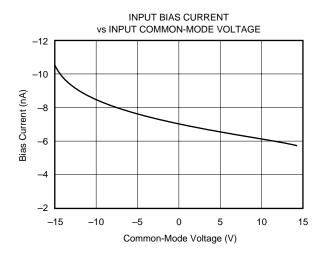


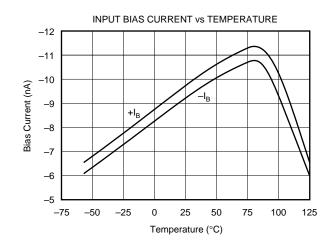


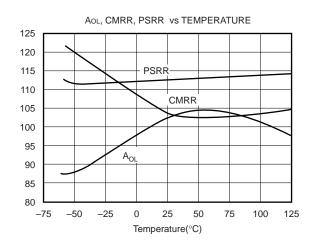


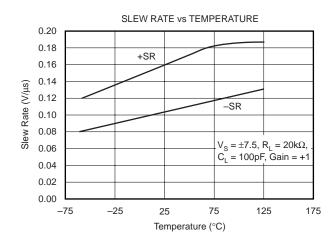


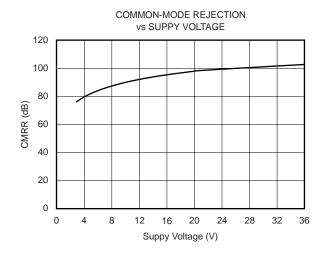
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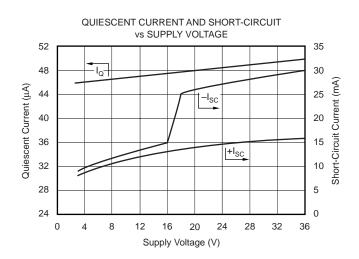




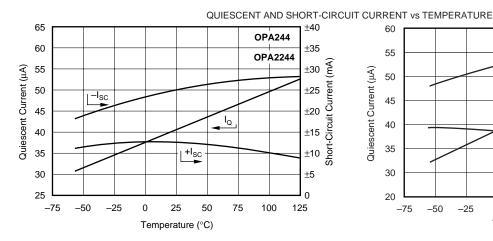


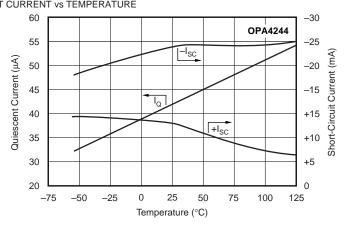


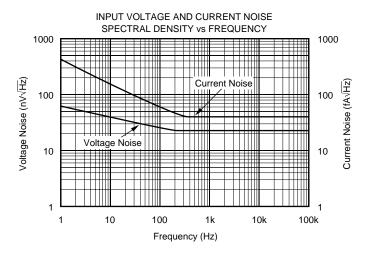


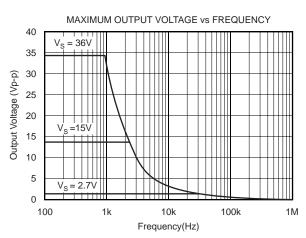


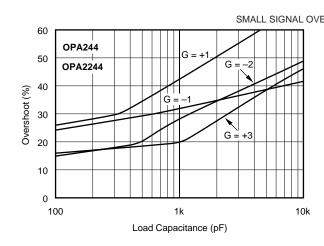
At T_A = 25°C, V_S = +15V, and R_L = 20k Ω connected to Ground, unless otherwise noted.

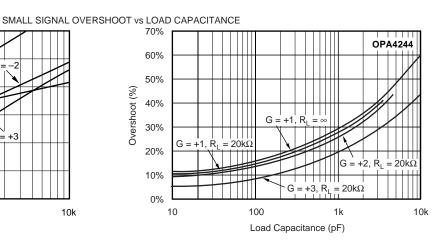






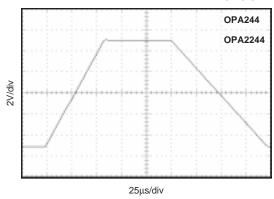


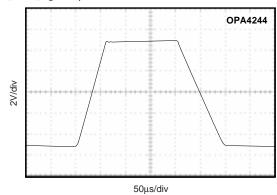




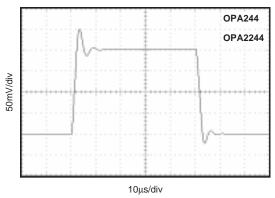
At T_A = 25°C, V_S = +15V, and R_L = 20k Ω connected to Ground, unless otherwise noted.

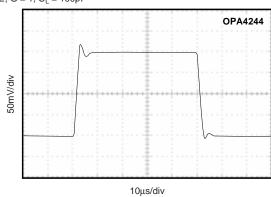
LARGE-SIGNAL STEP RESPONSE, G = 1, $C_L = 100pF$



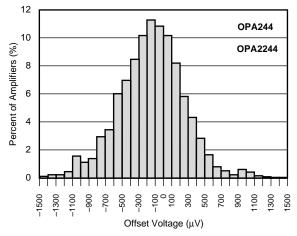


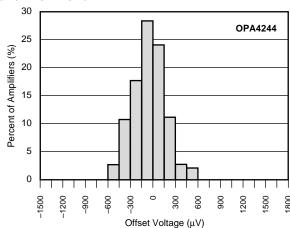
SMALL-SIGNAL STEP RESPONSE, G = 1, $C_L = 100pF$



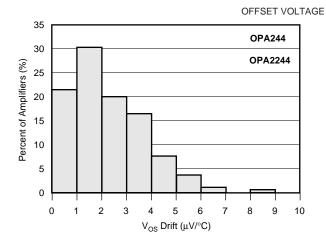


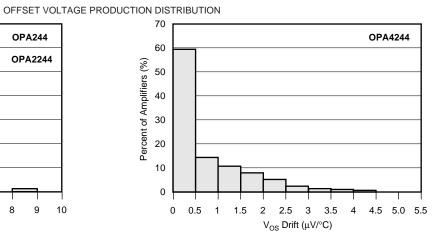
OFFSET VOLTAGE PRODUCTION DISTRIBUTION





At T_A = 25°C, V_S = +15V, and R_L = 20k Ω connected to Ground, unless otherwise noted.





APPLICATIONS INFORMATION

The OPA244 is unity-gain stable and suitable for a wide range of general purpose applications. Power supply pins should be bypassed with $0.01\mu F$ ceramic capacitors.

OPERATING VOLTAGE

The OPA244 can operate from single supply (+2.2V to +36V) or dual supplies (±1.1 to $\pm18V$) with excellent performance. Unlike most op amps which are specified at only one supply voltage, the OPA244 is specified for real world applications; a single set of specifications applies throughout the +2.6V to +36V (±1.3 to $\pm18V$) supply range.

This allows a designer to have the same assured performance at any supply voltage within this range. In addition, many key parameters are guaranteed over the specified temperature range, –40°C to +85°C. Most behavior remains unchanged throughout the full operating voltage range. Parameters which vary significantly with operating voltage or temperature are shown in typical performance curves.

Useful information on solder pad design for printed circuit boards can be found in Burr-Brown's Application Bulletin AB-132B, "Solder Pad Recommendations for Surface-Mount Devices," easily found at Burr-Brown's web site (http://www.burr-brown.com).

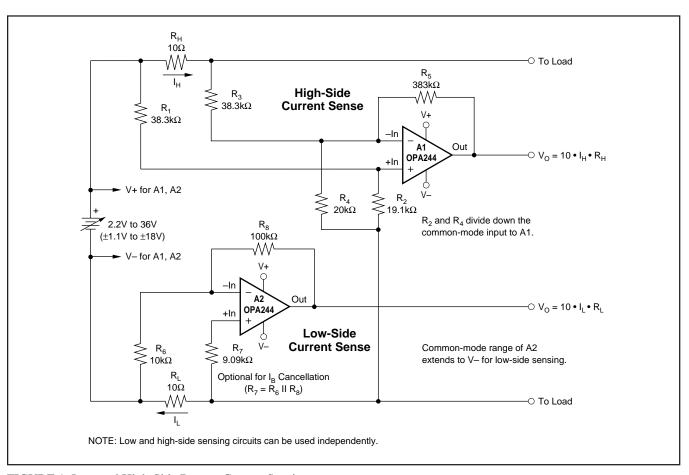


FIGURE 1. Low and High-Side Battery Current Sensing.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
OPA2244EA/250	LIFEBUY	VSSOP	DGK	8	250	RoHS & Green	NIPDAU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	A44	
OPA2244EA/250G4	LIFEBUY	VSSOP	DGK	8	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A44	
OPA2244EA/2K5	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A44	Samples
OPA2244EA/2K5G4	ACTIVE	VSSOP	DGK	8	2500	TBD	Call TI	Call TI	-40 to 85		Samples
OPA2244PA	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type		OPA2244PA	Samples
OPA2244UA	LIFEBUY	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-3-260C-168 HR		OPA 2244UA	
OPA2244UA/2K5	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR		OPA 2244UA	Samples
OPA2244UAG4	LIFEBUY	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-3-260C-168 HR		OPA 2244UA	
OPA244NA/250	LIFEBUY	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A44	
OPA244NA/250G4	LIFEBUY	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A44	
OPA244NA/3K	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A44	Samples
OPA244UA	LIFEBUY	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 244UA	
OPA244UA/2K5	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 244UA	Samples
OPA4244EA/250	LIFEBUY	TSSOP	PW	14	250	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 4244EA	
OPA4244EA/2K5	ACTIVE	TSSOP	PW	14	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 4244EA	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. **PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

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(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2244EA/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2244EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2244UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA244NA/250	SOT-23	DBV	5	250	178.0	8.4	3.3	3.2	1.4	4.0	8.0	Q3
OPA244NA/3K	SOT-23	DBV	5	3000	178.0	8.4	3.3	3.2	1.4	4.0	8.0	Q3
OPA244UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4244EA/250	TSSOP	PW	14	250	180.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
OPA4244EA/2K5	TSSOP	PW	14	2500	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2244EA/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2244EA/2K5	VSSOP	DGK	8	2500	356.0	356.0	35.0
OPA2244UA/2K5	SOIC	D	8	2500	356.0	356.0	35.0
OPA244NA/250	SOT-23	DBV	5	250	565.0	140.0	75.0
OPA244NA/3K	SOT-23	DBV	5	3000	565.0	140.0	75.0
OPA244UA/2K5	SOIC	D	8	2500	356.0	356.0	35.0
OPA4244EA/250	TSSOP	PW	14	250	210.0	185.0	35.0
OPA4244EA/2K5	TSSOP	PW	14	2500	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
OPA2244PA	Р	PDIP	8	50	506	13.97	11230	4.32
OPA2244UA	D	SOIC	8	75	506.6	8	3940	4.32
OPA2244UAG4	D	SOIC	8	75	506.6	8	3940	4.32
OPA244UA	D	SOIC	8	75	506.6	8	3940	4.32



SMALL OUTLINE TRANSISTOR



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE INTEGRATED CIRCUIT



- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



DGK (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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